



07/28/2004

RELIABILITY MONITOR REPORT
FOR

CSBGA Interposer Package

Dallas Semiconductor

4401 South Beltwood Parkway
Dallas, TX 75244-3292

This Report was prepared by
Dallas Semiconductor Reliability Engineering

Summary:

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The assemblies covered by this package monitor are:

ASSY SITE	PINS	PACKAGE		
ASAT	144	CSBGA Interposer	ASAT	256 CSBGA Interposer
Dallas	144	CSBGA Interposer		

Note: Due to the nature of the construction on this assembly, there is no operating life data collected

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 07/01/2003 and 06/30/2004.

Assembly Information:

Package Type: CSBGA Interposer 27 mm
 Flammability: UL 94-V0
 Moisture Sensitivity (JEDEC J-STD20A) Level 4
 Date Code Range: 0334 to 0334

PRECONDITIONING LEVEL 4

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
STORAGE LIFE	0334	DS21Q55	125C	24 HRS	77		
MOISTURE SOAK			30C/60% R.H.	96 HRS	77		
CONVECTION REFLOW			220C	3 PASS	77	0	
Total:						0	

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
TEMP CYCLE, SLOW	0334	DS21Q55	-40C TO +125C	1000 CYS	77	1	30018311
Total:						1	